

IN THE CLAIMS:

Please substitute the following claims for the same-numbered claims in the application:

1. (Currently Amended) An integrated circuit structure including a portion of a conductive layer, said portion of a conductive layer comprising:

~~an insulator layer;~~

~~a pad comprising a conductive material on said insulator layer, said pad having a wirebond connection region and a probe pad region; and~~

~~an inspection mark between said wirebond connection region and said probe pad region, wherein said inspection mark comprises an opening in said insulator layer that is filled with said conductive material,~~

~~wherein said probe pad region is adapted to make physical contact with a probe;~~

~~wherein said probe pad region and said inspection mark are visible from an exterior of said integrated circuit structure, and~~

~~wherein said probe pad region and said inspection mark each comprise a portion of said conductive material~~

a wire bond region;

a probe pad region in which a probe mark is located, said probe mark including a visible area of damage; and

an inspection mark including a contour structure that is topographically visible for inspection and that marks a boundary between said wire bond region and said probe pad region.

2. (Currently Amended) The integrated circuit structure in claim 1, all the limitations of which are incorporated herein by reference, further comprising a ~~polyimide~~ passivation layer above said portion of a conductive material layer, said ~~polyimide~~ having a second passivation layer including an opening, wherein said pad is exposed through said second opening through which said portion of a conductive layer is visible for inspection.

3. (Currently Amended) The integrated circuit structure in claim 1, all the limitations of which are incorporated herein by reference, ~~wherein said inspection mark opening is formed above~~ further comprising an insulating ~~region of said wiring~~ layer underlying said portion of a conductive layer.

wherein an inspection mark opening is formed in said insulating layer, and
wherein said contour structure of said portion of a conductive layer overlies said
inspection mark opening.

4. (Currently Amended) The integrated circuit structure in claim 1, all the limitations of which are incorporated herein by reference, wherein said portion of a conductor layer comprises a refractory metal.

5. (Currently Amended) The integrated circuit structure in claim 1, all the limitations of which are incorporated herein by reference, wherein said portion of a conductor layer comprises ~~one~~ any of aluminum, tantalum, and titanium, ~~and alloys thereof~~.

6. (Cancelled).

7. (Cancelled).

8. (Currently Amended) An integrated circuit structure comprising:
a wiring layer ~~below said insulator layer~~ said wiring layer comprising including a conductor wire;
an insulator layer, including an inspection mark opening, on said wiring layer;
~~a pad comprising~~ a conductive ~~material~~ layer on said insulator layer, ~~said pad having a wirebond connection region and a probe pad region~~ wherein said conductive layer includes a topographical contour that overlies said inspection mark opening; and
~~an inspection mark between said wirebond connection region and said probe pad region, wherein said inspection mark comprises an opening in said insulator layer that is filled with said~~

~~conductive material, wherein said probe pad region is adapted to make physical contact with a probe, wherein said probe pad region and said inspection mark are visible from an exterior of said integrated circuit structure, and wherein said probe pad region and said inspection mark each comprise a portion of said conductive material; and~~

~~a contact through said insulator layer, said contact being adapted to electrically connect said conductor wire in said wiring layer to said pad, wherein said contact comprises said conductive material~~

a passivation layer on said conductive layer, said passivation layer including an opening through which a portion of said conductive layer including said topographical contour that overlies said inspection mark opening is visible for inspection,

wherein said topographical contour delineates said portion of said conductive layer visible for inspection into a wire bond region and a probe pad region, and

wherein said probe pad region includes a visible area of damage.

9. (Cancelled).

10. (Currently Amended) The integrated circuit structure in claim 8, all the limitations of which are incorporated herein by reference, wherein said inspection mark opening is formed above an insulating region of said wiring layer.

11. (Currently Amended) The integrated circuit structure in claim 8, all the limitations of which are incorporated herein by reference, wherein said conductor comprises a refractory metal.

12. (Currently Amended) The integrated circuit structure in claim 8, all the limitations of which are incorporated herein by reference, wherein said conductor comprises ~~one~~ any of aluminum, tantalum, and titanium, ~~and alloys thereof~~.

13-20. (Cancelled).

21. (Currently Amended) An integrated circuit structure comprising:

- a wiring layer ~~below said insulator layer~~ ~~said wiring layer comprising~~ including a conductor wire;
- an insulator layer, including a wiring contact opening and an inspection mark opening, on said wiring layer;
- ~~a pad comprising~~ a conductive material layer on said insulator layer, ~~said pad having a wirebond connection region and a probe pad region~~ wherein said conductive layer includes a first topographical contour that overlies said wiring contact opening and a second topographical contour that overlies said inspection mark opening; and
- ~~an inspection mark between said wirebond connection region and said probe pad region, wherein said inspection mark comprises an opening in said insulator layer that is filled with said conductive material,~~
- ~~wherein said inspection mark delineates where probe inspection marks are permitted on said pad,~~
- ~~wherein said probe pad region is adapted to make physical contact with a probe,~~
- ~~wherein said probe pad region and said inspection mark are visible from an exterior of said integrated circuit structure, and~~
- ~~wherein said probe pad region and said inspection mark each comprise a portion of said conductive material; and~~
- ~~a contact through said insulator layer, said contact being adapted to electrically connect said conductor wire in said wiring layer to said pad, wherein said contact comprises said conductive material~~
- a passivation layer on said conductive layer, said passivation layer including an opening through which a portion of said conductive layer including said second topographical contour that overlies said inspection mark opening is visible for inspection,
- wherein said second topographical contour delineates said portion of said conductive layer visible for inspection into a wire bond region and a probe pad region, and
- wherein said probe pad region includes a visible area of damage.

22. (Cancelled).

23. (Currently Amended) The integrated circuit structure in claim [[1]] 21, all the limitations of which are incorporated herein by reference, wherein said inspection mark opening is formed above an insulating region of said wiring layer.

24. (Currently Amended) The integrated circuit structure in claim [[1]] 21, all the limitations of which are incorporated herein by reference, wherein said conductor comprises a refractory metal.

25. (Currently Amended) The integrated circuit structure in claim [[1]] 21, all the limitations of which are incorporated herein by reference, wherein said conductor comprises ~~one~~ any of aluminum, tantalum, and titanium, ~~and alloys thereof~~.

26. (New) The integrated circuit structure of claim 1, all the limitations of which are incorporated herein by reference, further comprising a connecting wire bonded to said wire bond region via a solder ball.

27. (New) The integrated circuit structure in claim 8, all the limitations of which are incorporated herein by reference, further comprising an insulating layer underlying said portion of a conductive layer,

wherein an inspection mark opening is formed in said insulating layer, and

wherein said contour structure of said portion of a conductive layer overlies said inspection mark opening.

28. (New) The integrated circuit structure of claim 8, all the limitations of which are incorporated herein by reference, further comprising a connecting wire is bonded to said wire bond region via a solder ball.

29. (New) The integrated circuit structure in claim 21, all the limitations of which are incorporated herein by reference, further comprising an insulating layer underlying said portion of a conductive layer,

wherein an inspection mark opening is formed in said insulating layer, and

wherein said contour structure of said portion of a conductive layer overlies said inspection mark opening.

30. (New) The integrated circuit structure of claim 21, all the limitations of which are incorporated herein by reference, further a connecting wire is bonded to said wire bond region via a solder ball.